



GP-2835  
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BD  
C-12-9

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul Robert Hoffman  
Assignee: Amkor Technology, Inc.  
Title: LOOK DOWN IMAGE SENSOR PACKAGE AND FABRICATION  
METHOD  
Serial No.: 10/040,027 Filed: October 25, 2001  
Examiner: UNKNOWN Group Art 2835  
Docket No.: G0052 Unit:  
Group Art 2835  
Unit:

Monterey, CA  
November 27, 2002

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT  
UNDER §1.97(b)

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant wishes to call the following documents (a copy of each is enclosed) to the attention of the Examiner:

**U.S. PATENT DOCUMENTS**

	Document Number	Date	Name
1)	5,858,815	01/12/99	Heo et al.
2)	5,977,624	11/02/99	Heo et al.
3)	6,005,965	12/21/99	Tsuda et al.
4)	6,011,310	01/04/00	Naito et al.
5)	6,028,354	02/22/00	Hoffman
6)	2001/0013653A1	08/16/01	SHOJI
7)	6,291,884B1	09/18/01	Glenn et al.
8)	2002/0012234A1	01/31/02	HARADA et al.

**OTHER DOCUMENTS:**

1)	EE times, "Diminutive package holds Xicor E <sup>2</sup> PROM", <a href="http://www.eetimes.com/news/98/1022news/xicor.html">http://www.eetimes.com/news/98/1022news/xicor.html</a> , 8/17/98
2)	Substrate Technologies Incorporated, "Glossary", pages 1-3; <a href="http://www.sti-dallas.com/library/glossary.asp">http://www.sti-dallas.com/library/glossary.asp</a> , Date not available
3)	Value Added Services, page 1; <a href="http://www.valueaddedservices.net/glo.htm">http://www.valueaddedservices.net/glo.htm</a> , Date not available
4)	Universal Instruments Corporation, Binghamton, New York, 13902-0825, "Chip Scale Package Technology Wafer Scale Package Issues", <a href="http://www.uic.com/wcms/WCMS.nsf/index/White_Papers_7.html">http://www.uic.com/wcms/WCMS.nsf/index/White_Papers_7.html</a> , 7/17/00

A PTO form 1449 listing these documents is enclosed.

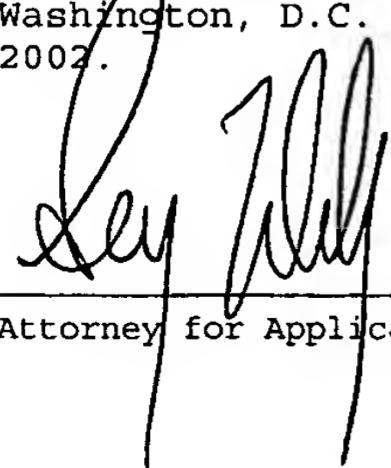
Citation of the above documents shall not be construed as:

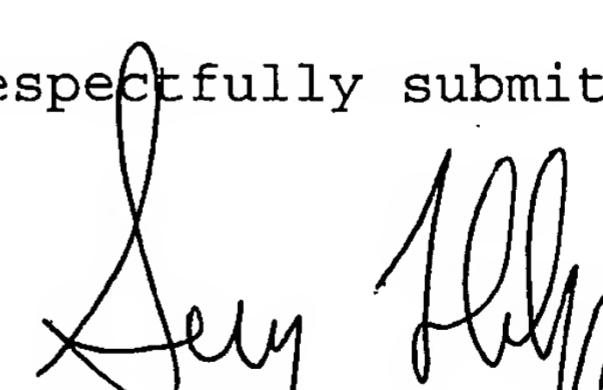
1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above; or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

If the USPTO issued a first office action prior to the mailing date of this paper, the Commissioner is hereby authorized to charge any fees required for consideration of this Information Disclosure Statement, and to credit any overpayment of fees to Deposit Account No. 50-0553.

**CERTIFICATE OF MAILING**

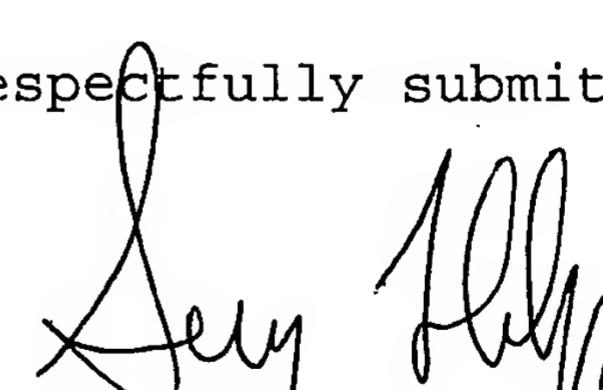
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on November 27, 2002.

  
Attorney for Applicant

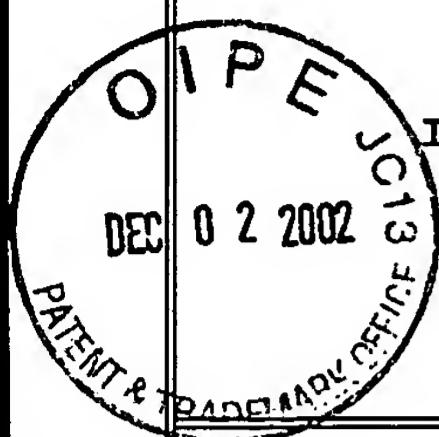
  
November 27, 2002

Date of Signature

Respectfully submitted,

  
Serge J. Hodgson  
Attorney for Applicant  
Reg. No. 40,017  
(831) 655-0880

Form PTO-1449



INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION  
*(Use several sheets if necessary)*

Atty Docket No.

G0052

Serial No.

107045/027

Applicant(s)

Paul Robert Hoffman

DEC-6 2002

Filing Date

October 25, 2001

TC 2800 MAIL ROOM

Group 2835

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,858,815	01/12/99	Heo et al.	438	112	
	AB	5,977,624	11/02/99	Heo et al.	257	701	
	AC	6,005,965	12/21/99	Tsuda et al.	382	145	
	AD	6,011,310	01/04/00	Naito et al.	257	774	
	AE	6,028,354	02/22/00	Hoffman	257	706	
	AF	2001/0013653A1	08/16/01	SHOJI	257	738	
	AG	6,291,884B1	09/18/01	Glenn et al.	257	747	
	AH	2002/0012234A1	01/31/02	HARADA et al.	361	778	
	AI						
	AJ						
	AK						

## FOREIGN PATENT DOCUMENTS

							Translation	
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
	AL							
	AM							
	AN							
	AO							
	AP							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AR	EE times, "Diminutive package holds Xicor E <sup>2</sup> PROM", <a href="http://www.eetimes.com/news/98/1022news/xicor.html">http://www.eetimes.com/news/98/1022news/xicor.html</a> , 8/17/98
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AT	Value Added Services, page 1; <a href="http://www.valueaddedservices.net/glo.htm">http://www.valueaddedservices.net/glo.htm</a> , Date not available

Examiner

Date Considered

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

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INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION

(Use several sheets if necessary)

Atty Docket No.

G0052

Serial No.

10/040,024

Applicant(s)

Paul Robert Hoffman

Filing Date

October 25, 2001

Group

2835

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## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
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	AH						
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	AK						

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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
	AL							
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	AP							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	AR	Universal Instruments Corporation, Binghamton, New York 13902-0825, "Chip Scale Package Technology Wafer Scale Package Issues", <a href="http://www.uic.com/wcms/WCMS.nsf/index/White_Papers_7.html">http://www.uic.com/wcms/WCMS.nsf/index/White_Papers_7.html</a> , 7/17/00
	AS	
	AT	

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